



STS5DNF20V

N-channel 20 V, 0.030 Ω , 5 A SO-8
2.7 V, drive STripFET™ II Power MOSFET

Features

Order code	V _{DSS}	R _{DS(on)} max.	I _D
STS5DNF20V	20 V	< 0.040 Ω @ 4.5 V < 0.045 Ω @ 2.7 V	5 A

- Ultra low threshold gate drive (2.7 V)
- Standard outline for easy automated surface mount assembly

Applications

Switching application

Description

The STS5DNF20V is a N-channel STripFET™ II. This Power MOSFET is the latest development of STMicroelectronics unique “single feature size” strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

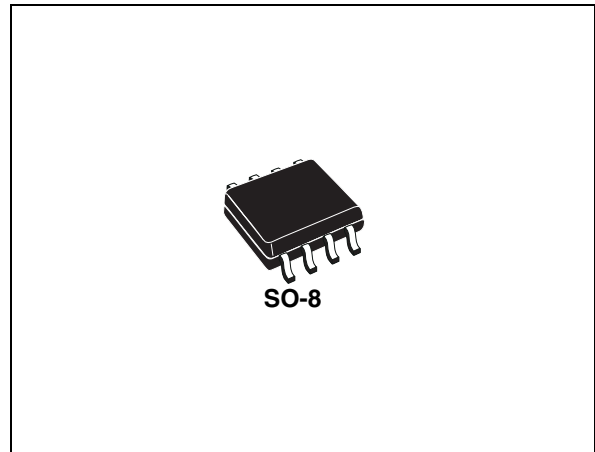


Figure 1. Internal schematic diagram

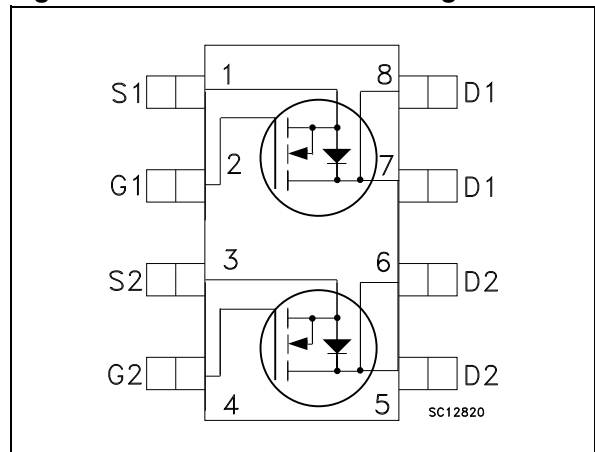


Table 1. Device summary

Order code	Marking	Package	Packaging
STS5DNF20V	5DNF20V	SO-8	Tape and reel

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	20	V
V_{GS}	Gate-source voltage	± 12	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	5	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	3	A
$I_{DM}^{(1)}$	Drain current (pulsed)	20	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$ (dual operation)	1.6	W
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$ (single operation)	2	W

1. Pulse width limited by safe operating area

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R_{thj-a}	Thermal resistance junction-ambient single operation	62.5	$^\circ\text{C/W}$
	Thermal resistance junction-ambient dual operation	78	$^\circ\text{C/W}$
T_J	Max. operating junction temperature	-55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature	-55 to 150	$^\circ\text{C}$

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	$I_D = 250\ \mu\text{A}$, $V_{GS} = 0$	20			V
I_{DSS}	Zero gate voltage Drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}$, $T_C = 125\text{ °C}$			1 10	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 12\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$	0.6			V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 4.5\text{ V}$, $I_D = 2.5\text{ A}$ $V_{GS} = 2.7\text{ V}$, $I_D = 2.5\text{ A}$		0.030 0.037	0.040 0.045	Ω Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance			460		pF
C_{oss}	Output capacitance	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$	-	200		pF
C_{rss}	Reverse transfer capacitance			50		pF
Q_g	Total gate charge	$V_{DD} = 16\text{ V}$, $I_D = 5\text{ A}$,		8.5	11.5	nC
Q_{gs}	Gate-source charge	$V_{GS} = 4.5\text{ V}$	-	1.8		nC
Q_{gd}	Gate-drain charge	(see Figure 13)		2.4		nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	$V_{DD}=10\text{ V}$, $I_D=2.5\text{ A}$, $R_G=4.7\Omega$, $V_{GS}=4.5\text{ V}$ (see Figure 12)	-	7	-	ns
				33		ns
$t_{d(off)}$ t_f	Turn-off Delay Time Fall Time			27		ns
				10		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		20	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 5\text{ A}$, $V_{GS} = 0$	-		1.2	V
t_{rr}	Reverse recovery time	$I_{SD} = 5\text{ A}$, $V_{DD} = 10\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 14)	-	26		ns
Q_{rr}	Reverse recovery charge			13		nC
I_{RRM}	Reverse recovery current			1		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

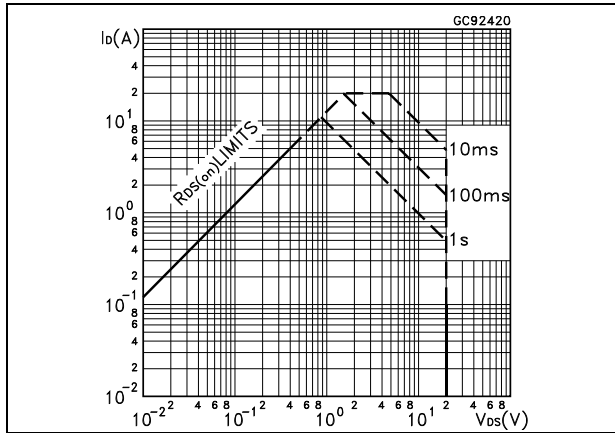


Figure 3. Thermal impedance

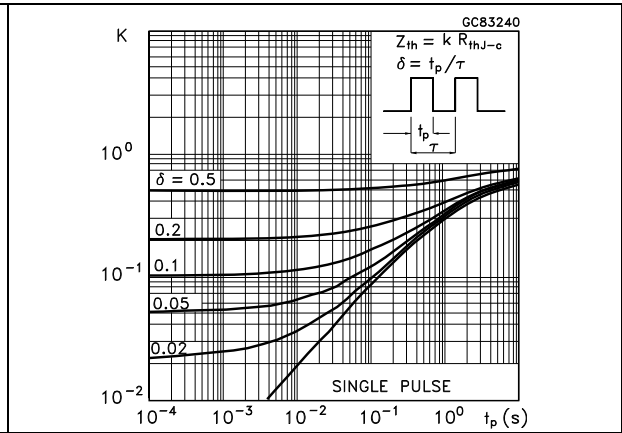


Figure 4. Output characteristics

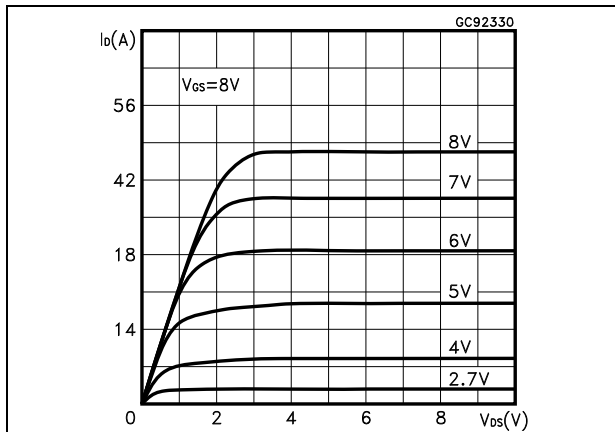


Figure 5. Transfer characteristics

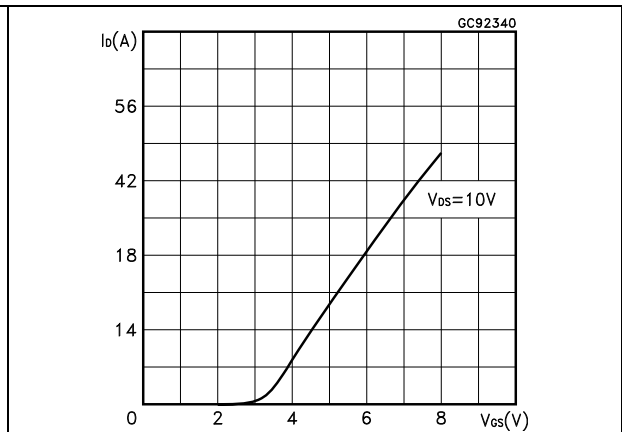


Figure 6. Source-drain diode forward characteristics

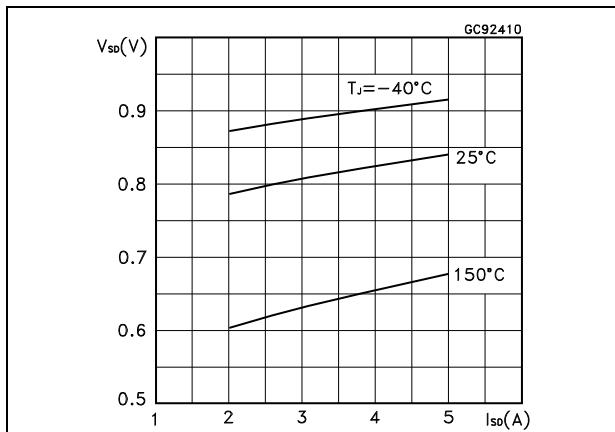


Figure 7. Static drain-source on resistance

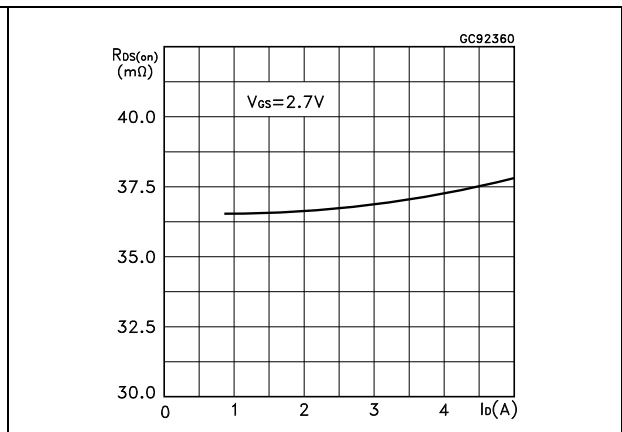


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

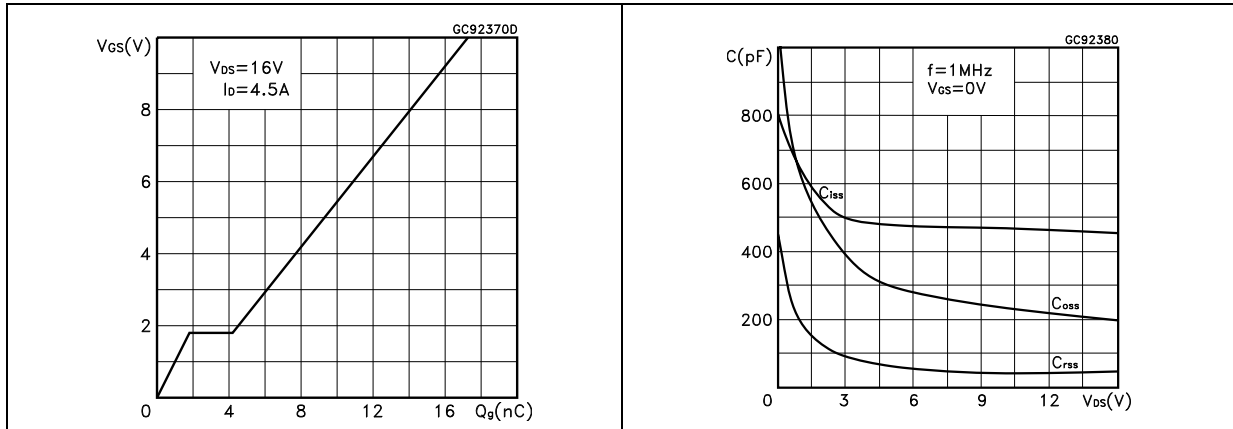
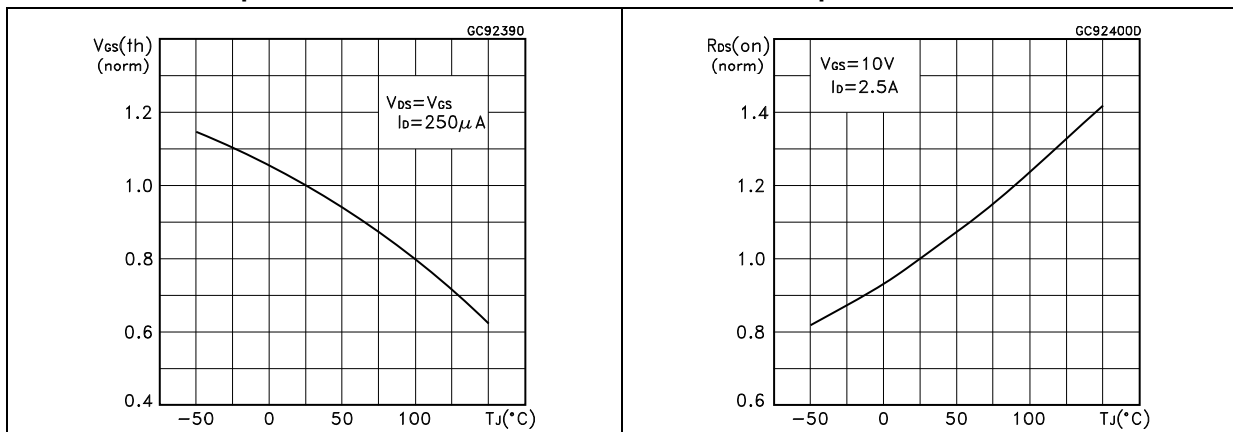
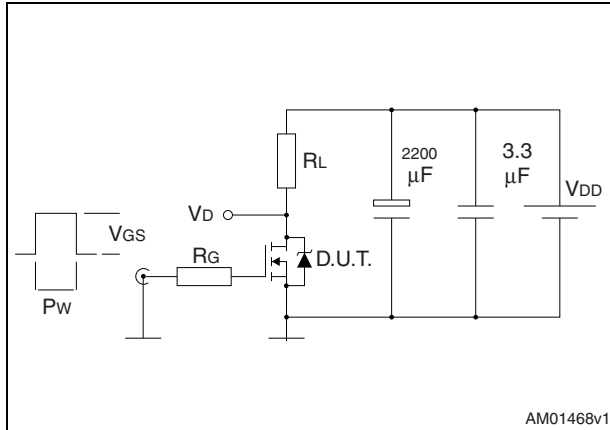


Figure 10. Normalized gate threshold voltage vs temperature Figure 11. Normalized on resistance vs temperature



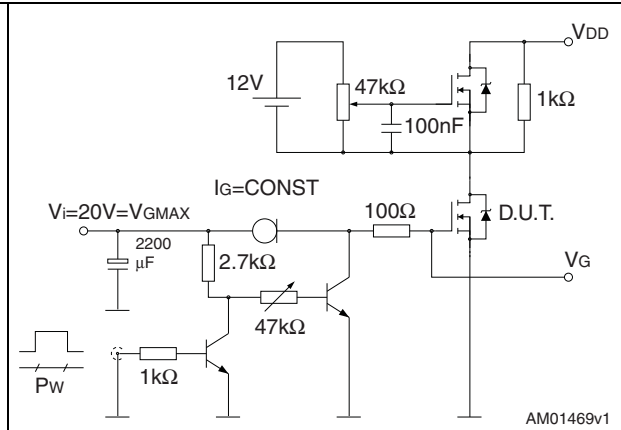
3 Test circuit

Figure 12. Switching times test circuit for resistive load



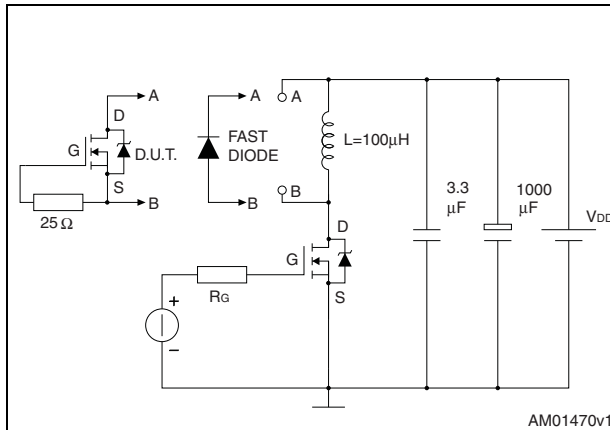
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Figure 13. Gate charge test circuit



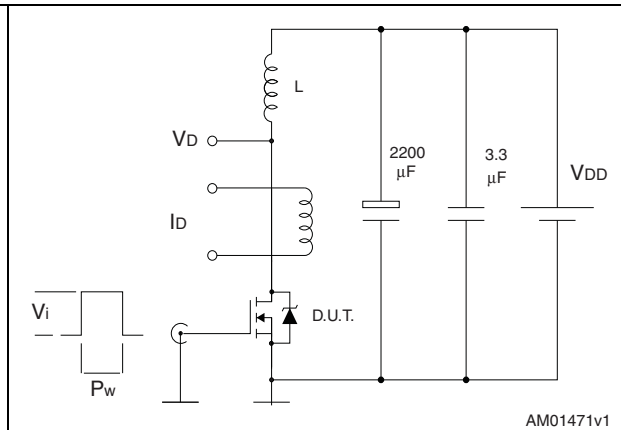
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Figure 14. Test circuit for inductive load switching and diode recovery times



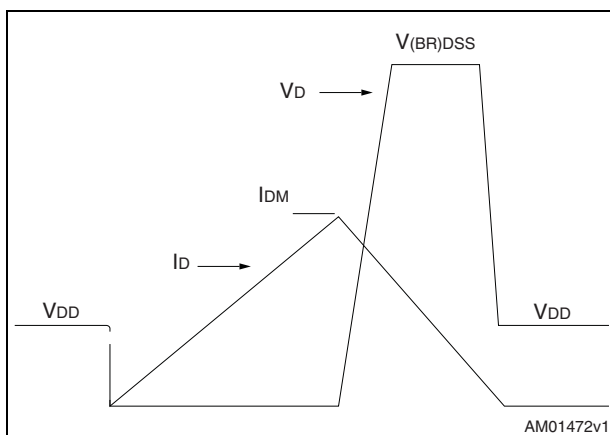
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Figure 15. Unclamped Inductive load test circuit



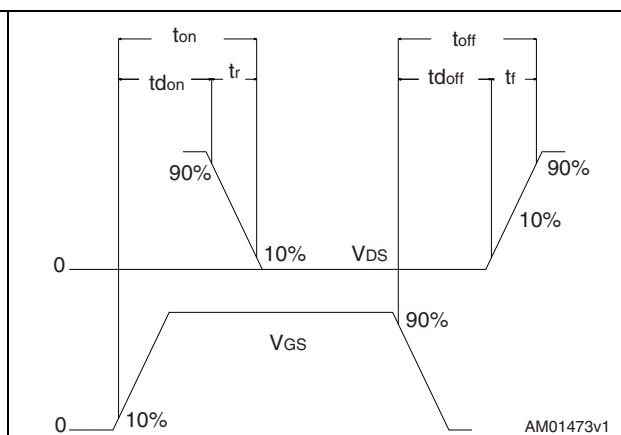
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Figure 16. Unclamped inductive waveform



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Figure 17. Switching time waveform



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4 Package mechanical data

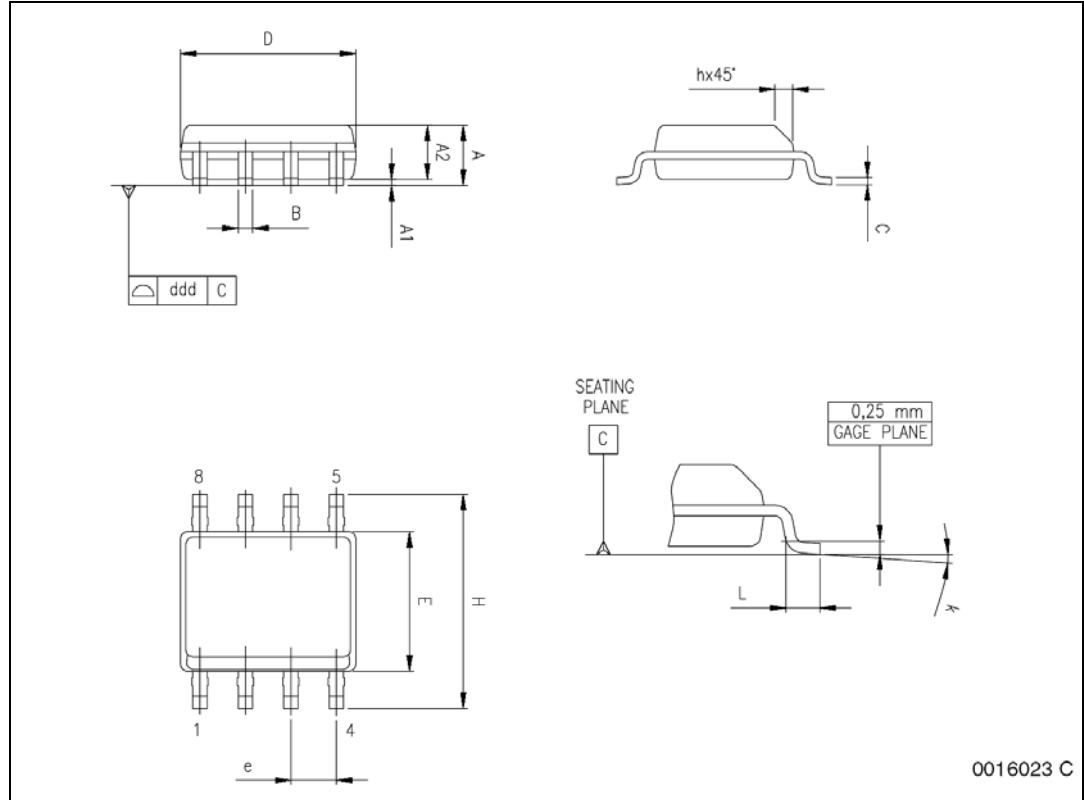
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Table 1. SO-8 mechanical data

Dim.	mm.			inch		
	Min	Typ	Max	Min	Typ	Max
A	1.35		1.75	0.053		0.069
A1	0.10		0.25	0.004		0.010
A2	1.10		1.65	0.043		0.065
B	0.33		0.51	0.013		0.020
C	0.19		0.25	0.007		0.010
D (1)	4.80		5.00	0.189		0.197
E	3.80		4.00	0.15		0.157
e		1.27			0.050	
H	5.80		6.20	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
k	0° (min.), 8° (max.)					
ddd			0.10			0.004

1. Dimensions D does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15mm (.006inch) in total (both side).

Figure 18. Package dimensions



5 Revision history

Table 8. Revision history

Date	Revision	Changes
21-Jun-2004	4	Complete document
13-Nov-2006	5	The document has been reformatted
02-May-2011	6	Table 1: Device summary has been corrected

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